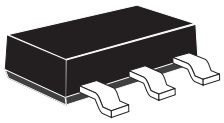
ZXMP3A16G

30V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY
$V_{(BR)DSS}$ = -30V: $R_{DS(on)}$ = 0.045Ω: I_D = -7.5A

DESCRIPTION

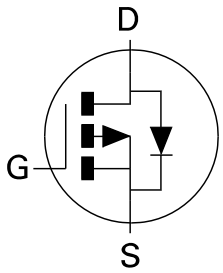
This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



SOT223

FEATURES

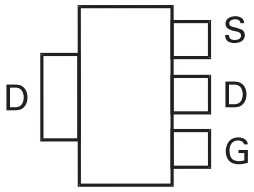
- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- SOT223 package



APPLICATIONS

- DC-DC converters
- Power management functions
- Relay and soleniod driving
- Motor control

PINOUT



Top View

ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMP3A16GTA	7″	12mm	1000 units
ZXMP3A16GTC	13″	12mm	4000 units

DEVICE MARKING

- ZXMP
  3A16

ABSOLUTE MAXIMUM RATING

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	-30	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current (V_{GS}= -10V; T_A=25°C)(b) (V_{GS}= -10V; T_A=70°C)(b) (V_{GS}= -10V; T_A=25°C)(a)	I_D	-7.5 -6.0 -5.4	A
Pulsed Drain Current (c)	I_{DM}	-24.9	A
Continuous Source Current (Body Diode) (b)	I_S	-3.2	A
Pulsed Source Current (Body Diode)(c)	I_{SM}	-24.9	A
Power Dissipation at T_A=25°C (a) Linear Derating Factor	P_D	2.0 16	W mW/°C
Power Dissipation at T_A=25°C (b) Linear Derating Factor	P_D	3.9 31	W mW/°C
Operating and Storage Temperature Range	T_j:T_{stg}	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	62.5	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	32.2	°C/W

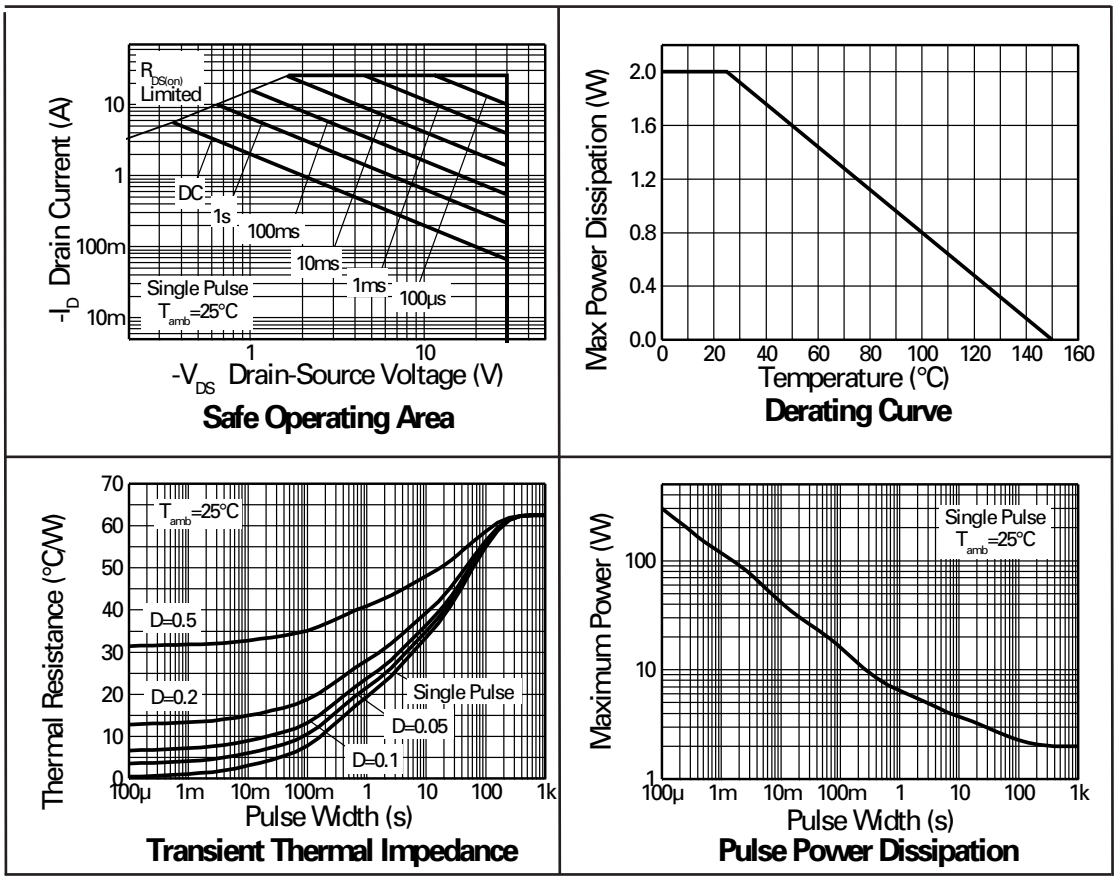
NOTES:

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at t≤10 secs.

(c) Repetitive rating 25mm x 25mm FR4 PCB, D=0.05 pulse width limited by maximum junction temperature.

TYPICAL CHARACTERISTICS

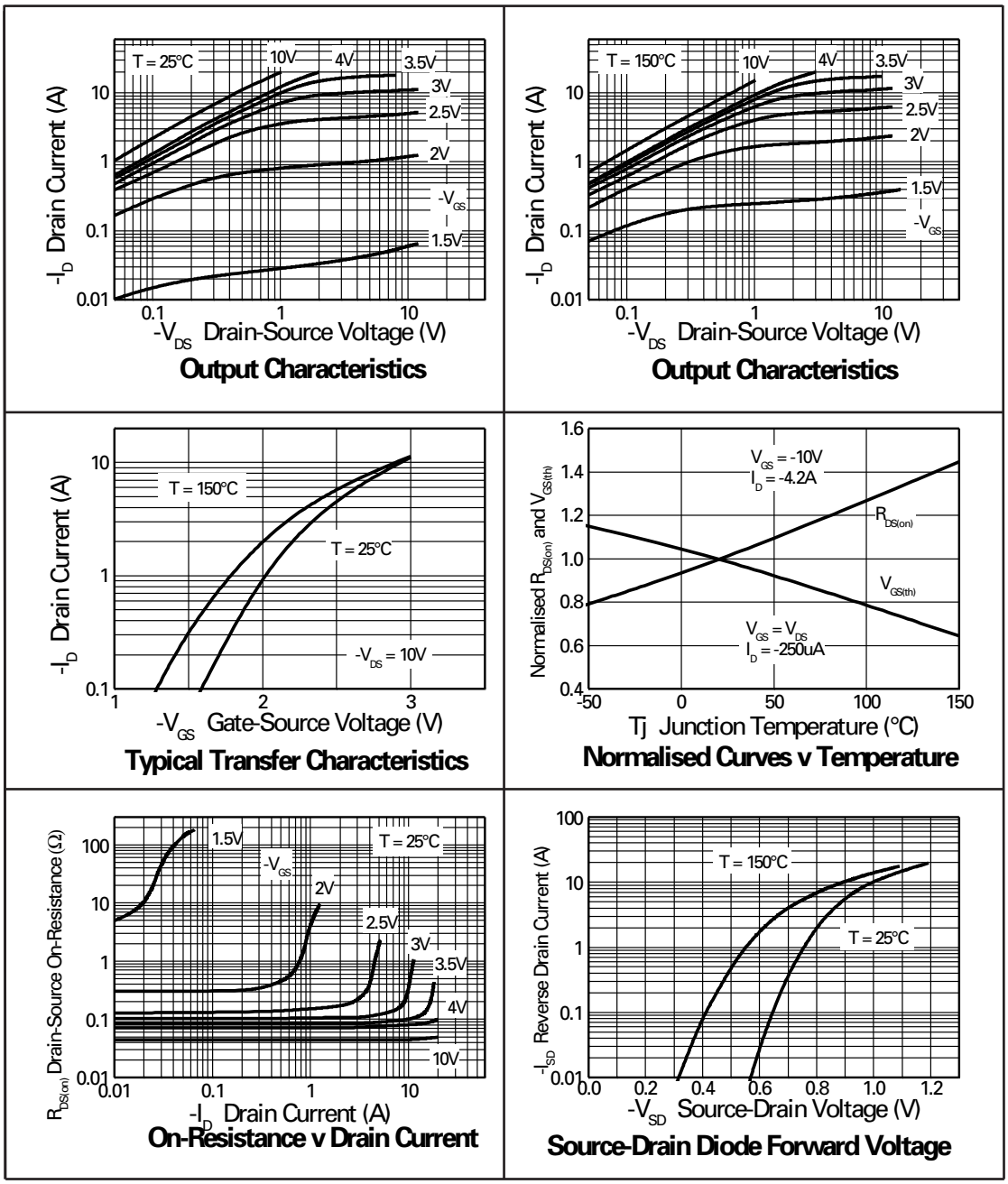


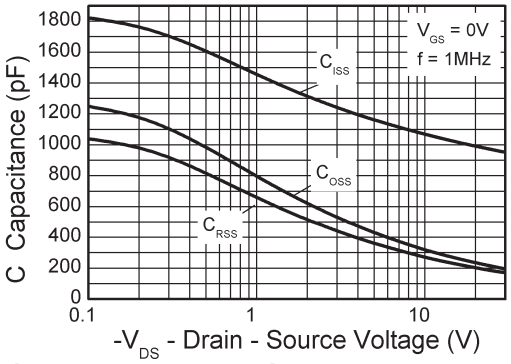
ELECTRICAL CHARACTERISTICS (at T_A = 25°C unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	-30			V	I_D=-250μA, V_{GS}=0V
Zero Gate Voltage Drain Current	I_{DSS}			-1	μA	V_{DS}=-30V, V_{GS}=0V
Gate-Body Leakage	I_{GSS}			100	nA	V_{GS}=±20V, V_{DS}=0V
Gate-Source Threshold Voltage	$V_{GS(th)}$	-1.0			V	I_D=-250μA, V_{DS}= V_{GS}
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.045 0.070	Ω Ω	V_{GS}=-10V, I_D=-4.2A V_{GS}=-4.5V, I_D=-3.4A
Forward Transconductance (1)(3)	g_{fs}		9.2		S	V_{DS}=-15V,I_D=-4.2A
DYNAMIC (3)						
Input Capacitance	C_{iss}		1022		pF	V_{DS}=-15V, V_{GS}=0V, f=1MHz
Output Capacitance	C_{oss}		267		pF	
Reverse Transfer Capacitance	C_{rss}		229		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	$t_{d(on)}$		3.8		ns	V_{DD} =-15V, I_D=-1A R_G=6.0Ω, V_{GS}=-10V
Rise Time	t_r		6.5		ns	
Turn-Off Delay Time	$t_{d(off)}$		37.1		ns	
Fall Time	t_f		21.4		ns	
Gate Charge	Q_g		17.2		nC	V_{DS}=-15V,V_{GS}=-5V, I_D=-4.2A
Total Gate Charge	Q_g		29.6		nC	V_{DS}=-15V,V_{GS}=-10V, I_D=-4.2A
Gate-Source Charge	Q_{gs}		2.8		nC	
Gate-Drain Charge	Q_{gd}		8.6		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}		-0.85	-0.95	V	T_J=25°C, I_S=-3.6A, V_{GS}=0V
Reverse Recovery Time (3)	t_{rr}		21.7		ns	T_J=25°C, I_F=-2A, di/dt= 100A/μs
Reverse Recovery Charge (3)	Q_{rr}		16.1		nC	

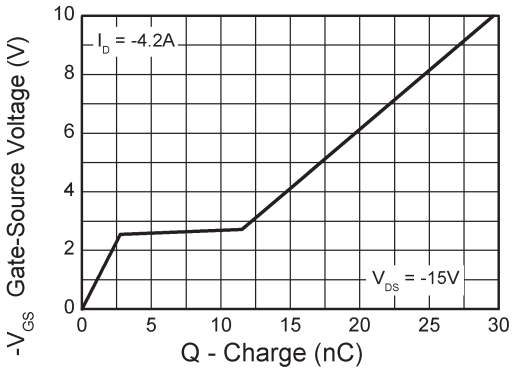
NOTES
(1) Measured under pulsed conditions. Width ≤300μ s. Duty cycle ≤ 2% .
(2) Switching characteristics are independent of operating junction temperature.
(3) For design aid only, not subject to production testing.

TYPICAL CHARACTERISTICS

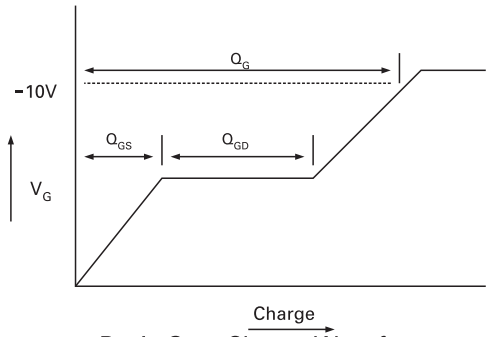




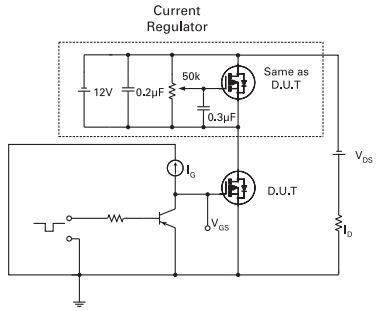
Capacitance v Drain-Source Voltage



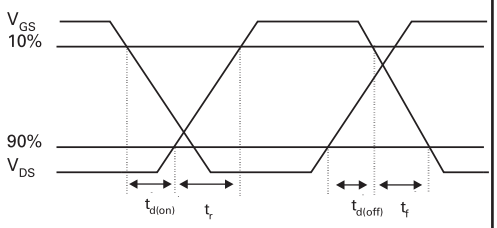
Gate-Source Voltage v Gate Charge



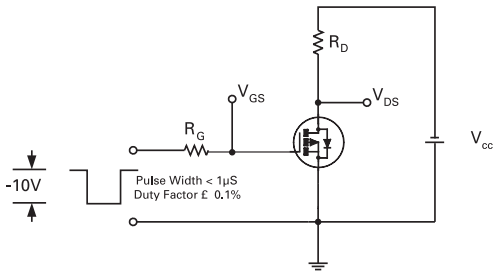
Basic Gate Charge Waveform



Gate Charge Test Circuit



Switching Time Waveforms



Switching Time Test Circuit

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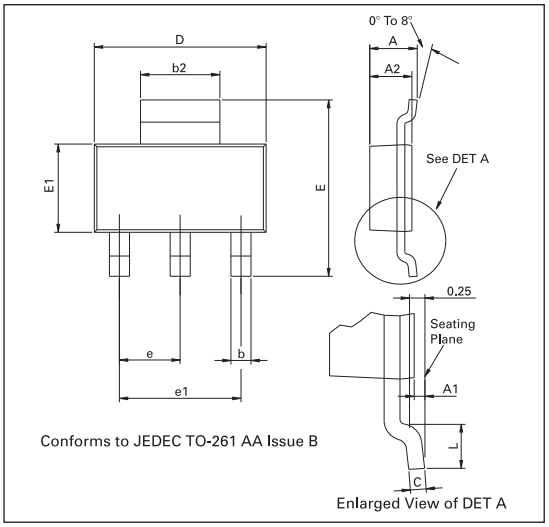
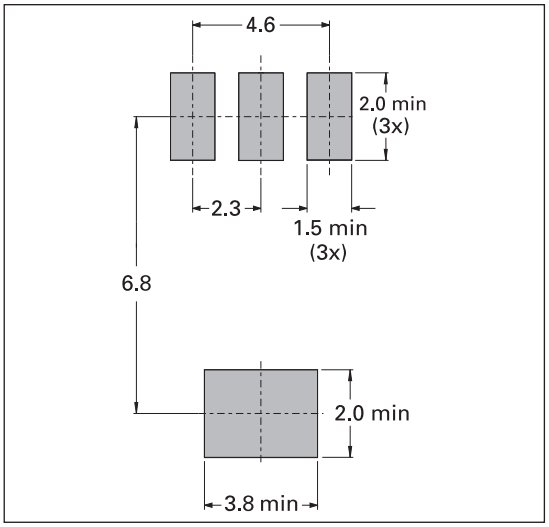
PACKAGE OUTLINE



PAD LAYOUT DETAILS



PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	-	1.80	-	0.071	e	2.30 BSC		0.0905 BSC	
A1	0.02	0.10	0.0008	0.004	e1	4.60 BSC		0.181 BSC	
b	0.66	0.84	0.026	0.033	E	6.70	7.30	0.264	0.287
b2	2.90	3.10	0.114	0.122	E1	3.30	3.70	0.130	0.146
C	0.23	0.33	0.009	0.013	L	0.90	-	0.355	-
D	6.30	6.70	0.248	0.264	-	-	-	-	-

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Europe	Americas	Asia Pacific	Corporate Headquarters
Zetex GmbH Kustermann-Park Balanstraße 59 D-81541 München Germany	Zetex Inc 700 Veterans Memorial Hwy Hauppauge, NY 11788 USA	Zetex (Asia) Ltd 3701-04 Metroplaza Tower 1 Hing Fong Road, Kwai Fong Hong Kong	Zetex Semiconductors plc Zetex Technology Park Chadderton, Oldham, OL9 9LL United Kingdom
Telefon: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com	Telephone: (1) 631 360 2222 Fax: (1) 631 360 8222 usa.sales@zetex.com	Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com	Telephone (44) 161 622 4444 Fax: (44) 161 622 4446 hq@zetex.com